

COMPANY PROFILE

„**SIEGERT WAFER GmbH** is your Partner for your Wafer demand with more than 10 years of experience.

We are Solution-Minded, Customer-Focused and we are committed to continually improve the effectiveness of our Service.

We support our customers from the idea to the final product and provide our strength in finding custom solutions for special requirements.“

ABOUT US

SIEGERT WAFER supplies custom and standard wafers for Universities and Research Labs as well as Industrial Customers all over the world. The continuous growth since the company was founded in 2002 proves that our products and services are state of the art. While quality is our main focus we also offer competitive prices. It is our goal to go the extra mile every day for maximum customer satisfaction.

We are able to ship all stock items within a day. Our inventory with thousands of wafers can be reviewed online at www.inventory.siebertwafer.com. If the desired specification is not available we can manufacture the wafers according to customer specifications within usual production times.



SIEGERT WAFER
Wafer Specialist

PRODUCTS

Silicon Wafers

Diameters: 50.8 - 300 mm
Grades: Prime, Test, Monitor,
Dummy, Reclaim
Growth: Czochralski (CZ)
Float Zone (FZ)
Surface: One or both sides polished,
as cut, etched, lapped
Resistivity: 0.001 - 50,000 ohm-cm
Thickness: 100 μ m - 10 mm
Ultra Flat
Intrinsic
Undoped

Glass Wafers

Diameters: 50.8 - 200 mm (or square)
Thickness: 150 μ m - 10 mm
Materials: BOROFLOAT
Fused Silica
Fused Quartz
Soda Lime
Eagle XG
BK7
D263
...

Silicon on Insulator (SOI)

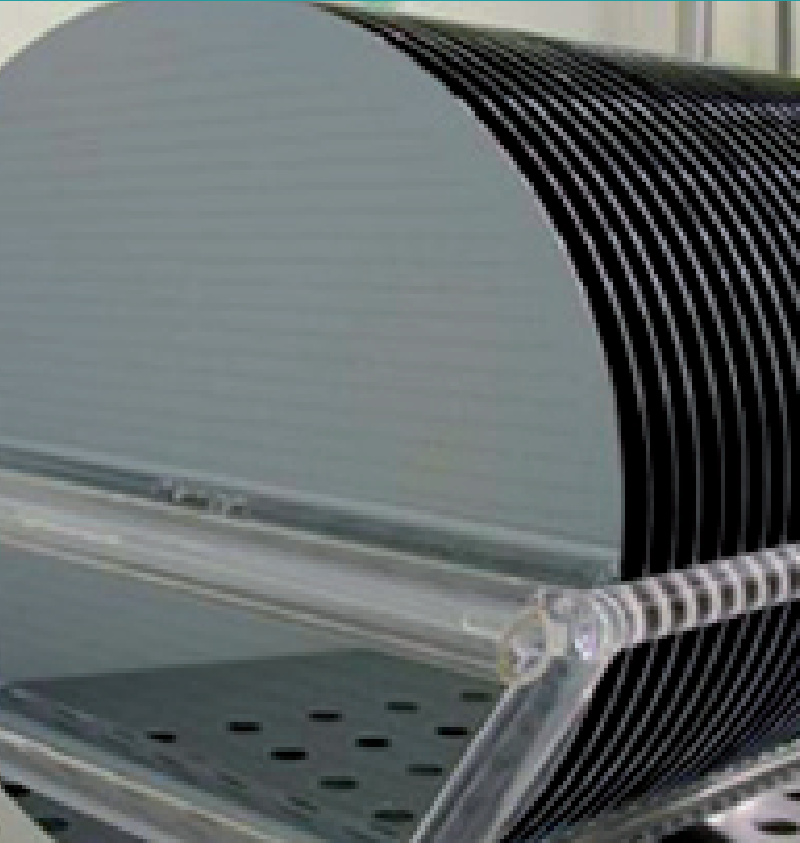
Diameters: 50.8 - 200 mm
Direct-Bonding
Epi-Layer-Transfer
Oxygen Implantation

Additional Materials

Sapphire
Germanium
III/V Materials
Mask Blanks
...



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SERVICES

Dicing

All kinds of Wafers, various formats

Lasermarking

Soft- und Hardlasermark

Metrology

SEM
AFM
STM
MFM
GDMS
Type- & Resistivity- check
Ellipsometry

Coatings

Various Metalizations
PVD / CVD / Electroplating / Evaporating
Dry and Wet Thermal Oxide
Low Temperature Oxide (LTO)
LPCVD Nitride
PECVD Nitride
Polysilicon
Photoresist
Anti Sticking Layer
ITO (Indium tin oxide)

Lithography

E-Beam
UV Nanoimprint
Optical Contact Lithography